

WHAT IS CLAIMED IS:

1. A trimming method of an electric circuit board including a glass substrate, and an electric circuit constituting element on or inside the glass substrate, said method comprising steps of

focusing an electromagnetic wave onto said predetermined electric circuit constituting element inside or on said glass substrate through said glass substrate; and

adjusting an electric property of said predetermined electric circuit constituting element positioned in the vicinity of a focus of said electromagnetic wave.

2. A trimming method of an electric circuit board including a glass substrate, an electric circuit constituting element inside the glass substrate, and a pair of electrodes disposed so as to hold the electric circuit constituting element therebetween, said method comprising steps of

focusing a laser beam emitted from a laser light source onto said predetermined electric circuit constituting element inside said glass substrate through said glass substrate in such a manner that said electrodes are avoided; and

adjusting an electric property of said predetermined electric circuit constituting element by irradiation with the laser beam for a short time.

3. A trimming method of an electric circuit

changing a state of said dielectric by  
irradiation with the laser beam for a short time and  
adjusting an electric property of the  
predetermined electric circuit constituting element.

7. The trimming method of the electric circuit board including the glass substrate according to claim

1, comprising a step of partially removing or cutting an electrode of an electric capacity disposed in said glass substrate and adjusting the electric property.

8. An electric circuit board including a glass substrate, comprising:

the glass substrate;

a wiring formed on a main surface and/or a back surface of the glass substrate; a plurality of external connection terminals electrically connected to the wiring;

and an external electric component connected to the external connection terminals,

wherein a state change portion is partially disposed inside said glass substrate.

9. An electric circuit board including a glass substrate, comprising:

the glass substrate;

a wiring formed on a main surface and/or a back surface of said glass substrate; a through hole and/or an end-surface wiring for electrically connecting the wiring formed on the main surface of said glass substrate to the main surface and the back surface of the glass substrate;

a plurality of external connection terminals formed on the back surface of said glass substrate and electrically connected to the wiring disposed on said main surface; and

an external component connected to some of

said external connection terminals,

wherein a state of said glass substrate is partially changed by irradiation of an electromagnetic wave focusing on the inside of the glass substrate.

10. The electric circuit board including the glass substrate according to claim 8, comprising: a superposed multilayered substrate; an electric capacity disposed on the multilayered substrate; and an electric capacity disposed by a state change in said glass substrate.

11. The electric circuit board including the glass substrate according to claim 10, wherein the electric capacity in said glass substrate is trimmed by irradiation with an electromagnetic wave and a combined electric capacity value is adjusted.

12. The electric circuit board including the glass substrate according to claim 8, wherein said electric circuit board is a liquid crystal panel in which a large number of electric circuit constituting elements are formed.

13. The electric circuit board including the glass substrate according to claim 8, comprising an electrode of an electric capacity formed on said glass substrate after the electric capacity is trimmed by a state change in said glass substrate.

14. A trimming method of an electric circuit board including a glass substrate, comprising:

a process of forming an electric circuit on a

[illegible]

glass substrate;

a process of forming a trimmable passive component;

a process of forming another passive component;

a process of mounting another component;

a process of measuring an electric property of a mounted circuit board;

a process of calculating a trimming amount from a measured value; and

a process of focusing on and irradiating the inside of the glass substrate with an electromagnetic wave based on the calculated trimming amount and subjecting a part of the inside of the glass substrate to state change.

15. A trimming apparatus of an electric circuit board including a glass substrate, comprising:

means for measuring an electric property of a mounted circuit board;

means for calculating a trimming amount from a measured value;

means for focusing on and irradiating the inside of the glass substrate with an electromagnetic wave based on the calculated trimming amount and partially trimming the inside of the glass substrate; and

means for managing information of said measured value and said trimming amount.